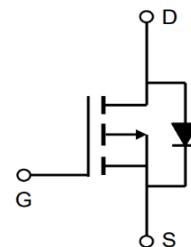


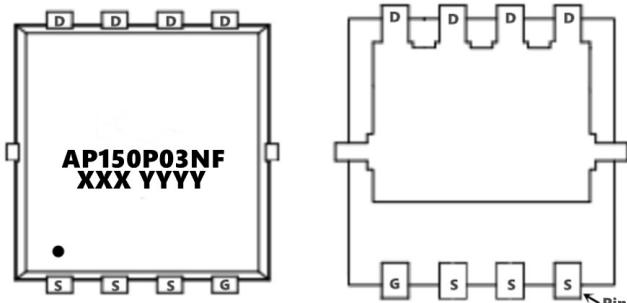
-30V P-Channel Enhancement Mode MOSFET
Description

The AP150P03NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.


General Features

$V_{DS} = -30V$ $I_D = -150A$

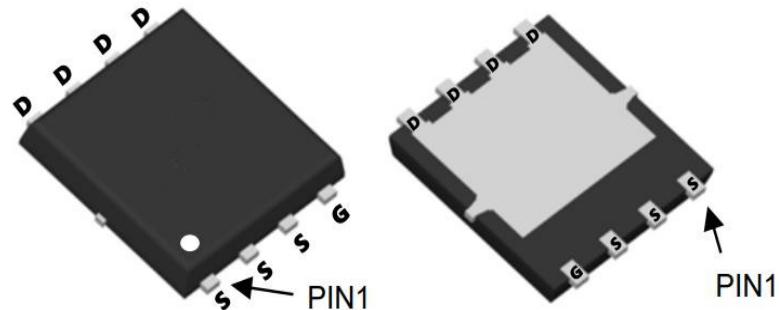
$R_{DS(ON)} < 3.2m\Omega$ @ $V_{GS} = -10V$ (Type: 2.5m Ω)


Application

Lithium battery protection

Wireless impact

Mobile phone fast charging


Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP150P03NF	PDFN5*6-8L	AP150P03NF XXX YYYY	5000

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-30	V
VGS	Gate-Source Voltage	± 20	V
ID@TC=25°C	Continuous Drain Current, VGS @ -10V1	-150	A
ID@TC=100°C	Continuous Drain Current, VGS @ -10V1	-75	A
IDM	Pulsed Drain Current2	-450	A
EAS	Single Pulse Avalanche Energy3	576	mJ
IAS	Avalanche Current	-70	A
PD@TC=25°C	Total Power Dissipation4	150	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-Ambient 1	25	°C/W
R _{θJC}	Thermal Resistance Junction-Case1	1.06	°C/W

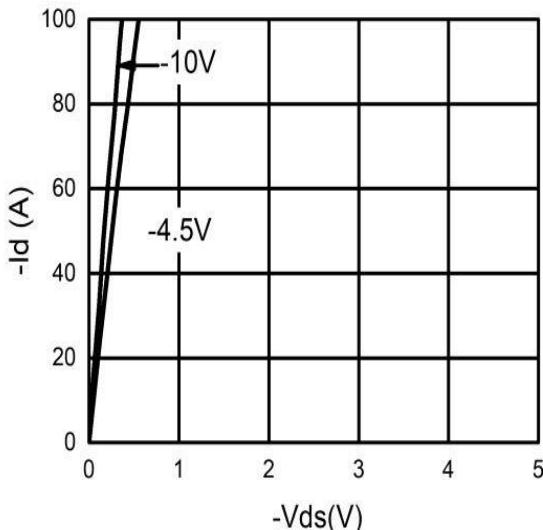
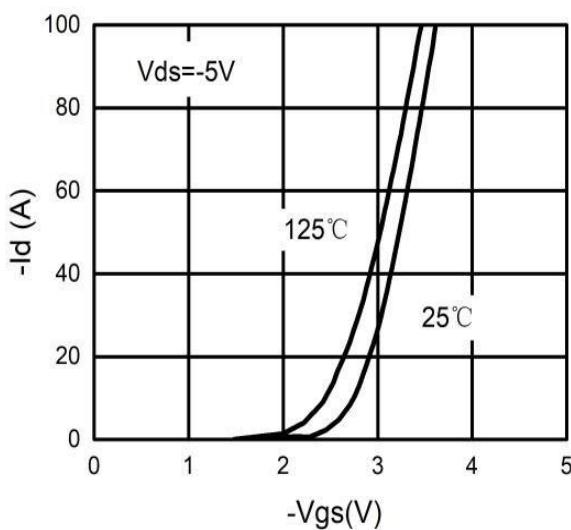
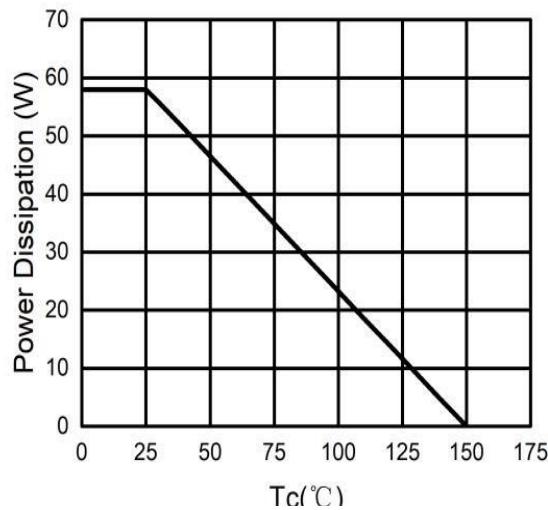
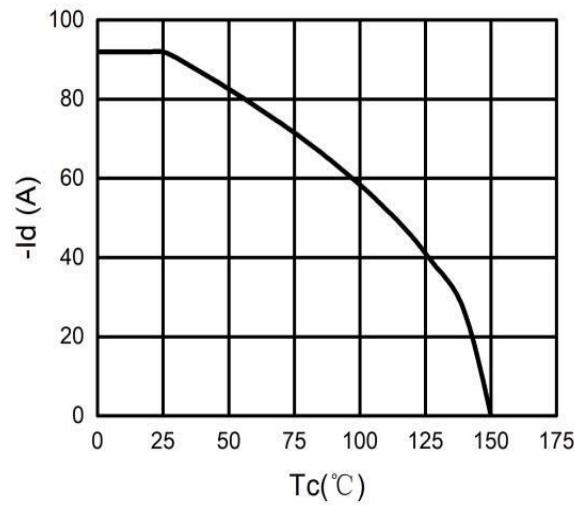
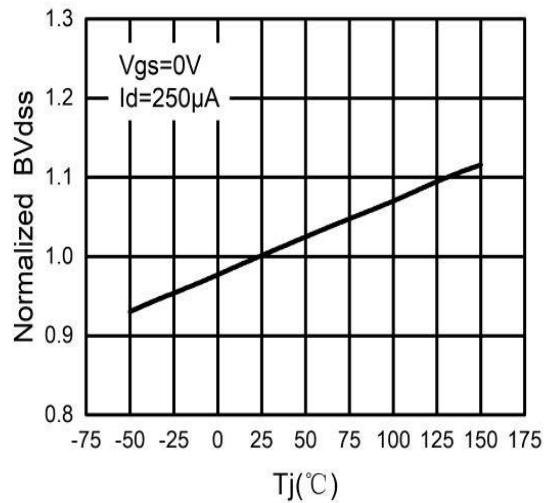
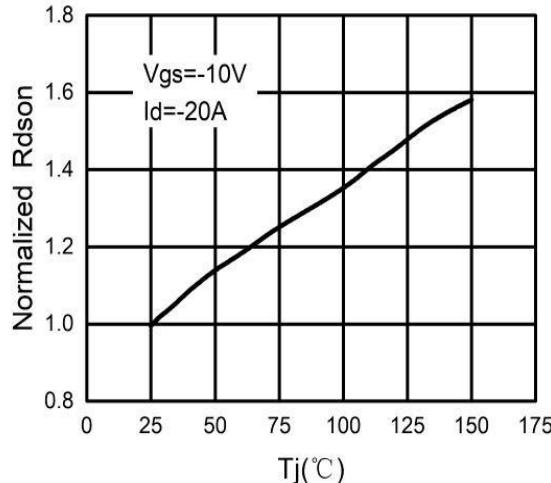


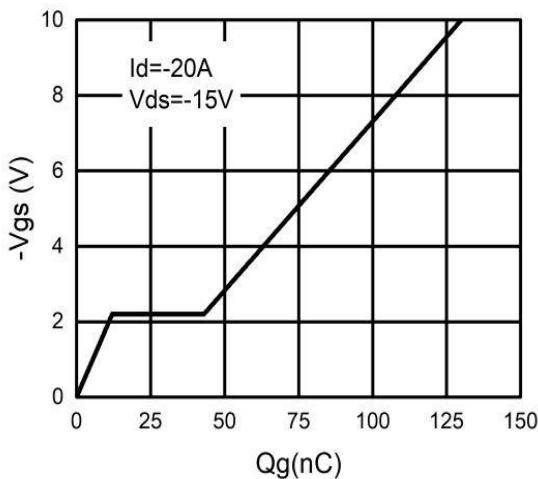
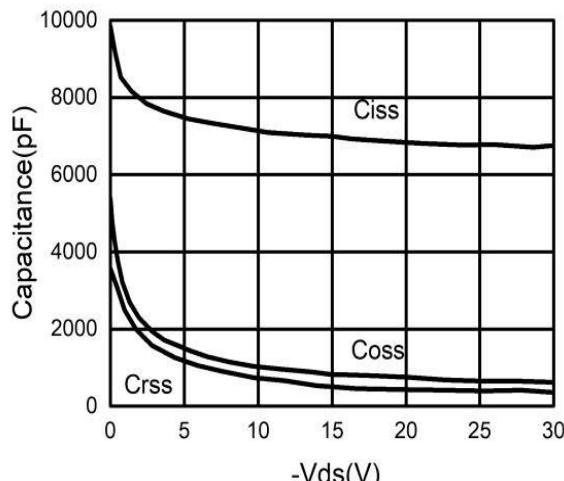
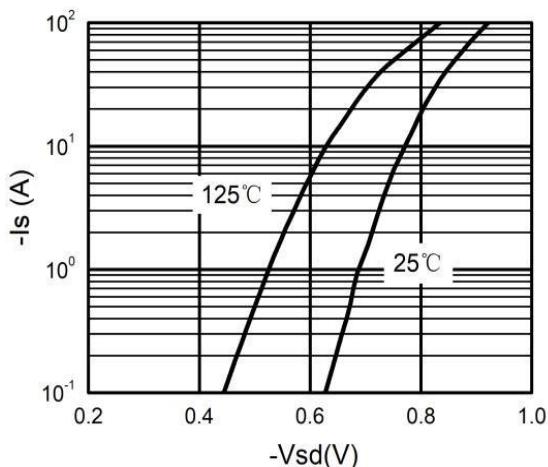
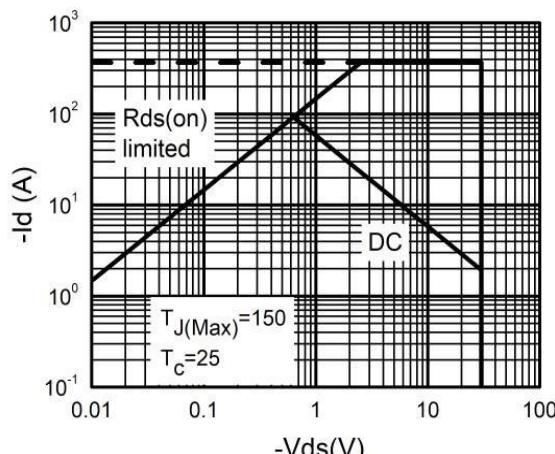
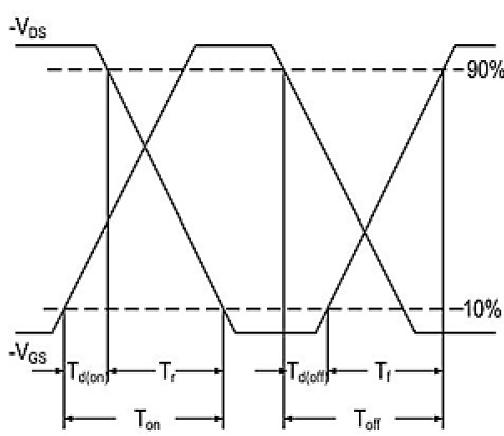
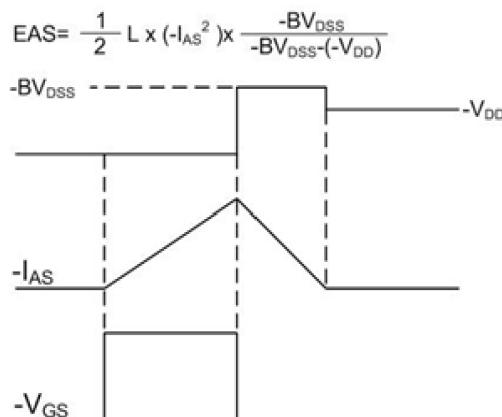
-30V P-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

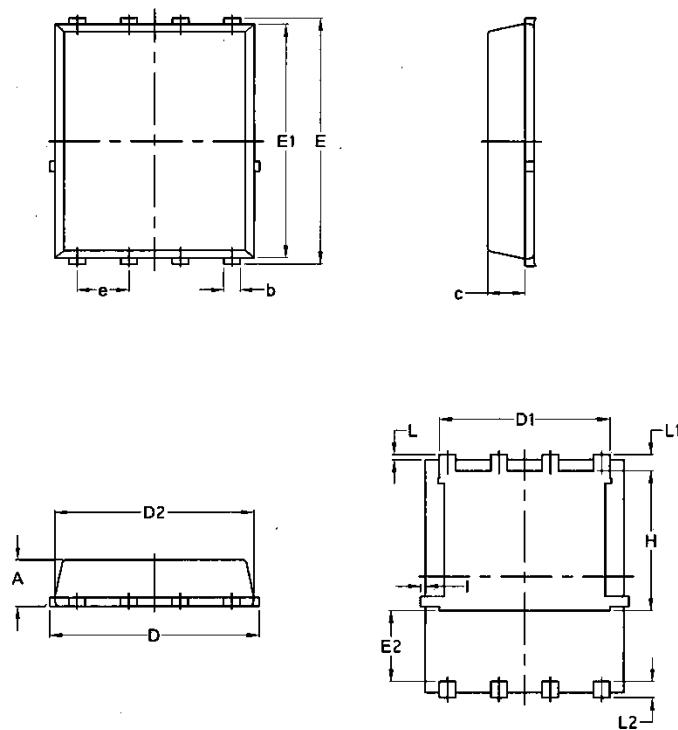
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	-35		V
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$			-1	μA
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm20\text{V}$, $V_{DS}=0\text{V}$			±100	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	-1	-1.7	-2.5	V
RDS(ON)	Drain-Source On-State Resistance	$V_{GS}=-10\text{V}$, $I_D=20\text{A}$		2.5	3.2	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=20\text{A}$		4.0	5.2	$\text{m}\Omega$
gFS	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=20\text{A}$		65		S
Ciss	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$		7000		pF
Coss	Output Capacitance			820		pF
Crss	Reverse Transfer Capacitance			540		pF
Rg	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1.0\text{MHz}$		2.2		Ω
td(on)	Turn-on Delay Time	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $R_L=0.75\Omega$, $R_{GEN}=3\Omega$		14		nS
t _r	Turn-on Rise Time			13		nS
td(off)	Turn-Off Delay Time			65		nS
t _f	Turn-Off Fall Time			37		nS
Q _g	Total Gate Charge	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $I_D=20\text{A}$		130		nC
Q _{gs}	Gate-Source Charge			12		nC
Q _{gd}	Gate-Drain Charge			31		nC
ISD	Source-Drain Current (Body Diode)				-150	A
VSD	Forward on Voltage ^(Note 3)	$V_{GS}=0\text{V}$, $I_S=20\text{A}$			-1.3	V
trr	Reverse Recovery Time	$I_F=-20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		30		ns
Q _{rr}	Reverse Recovery Charge	$I_F=-20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		40		nC

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $T_J =25^{\circ}\text{C}$, $VDD=-15\text{V}$, $VG=-10\text{V}$, $RG=25\Omega$, $L=0.5\text{mH}$, $IAS=-30\text{A}$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Power Dissipation

Figure 4. Drain Current

Figure 5. BV_{dss} vs Junction Temperature

Figure 6. $R_{DS(on)}$ vs Junction Temperature

-30V P-Channel Enhancement Mode MOSFET

Figure 7. Gate Charge Waveforms

Figure 8. Capacitance

Figure 9. Body-Diode Characteristics

Figure 10. Maximum Safe Operating Area

Figure.11 Switching Time Waveform

Figure.12 Unclamped Inductive Switching Waveform

-30V P-Channel Enhancement Mode MOSFET
Package Mechanical Data-DFN5*6-8L-JQ Single


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070